

DATASHEET

SMD • Low Power LED 45-21UMC/404589E/TR8-T



Features

- · PLCC-2 package
- · Top view white LED
- High luminous Intensity output
- Wide viewing angle
- · Pb-free
- RoHS compliant
- Compliance with EU REACH
- Compliance Halogen Free .(Br <900 ppm ,Cl <900 ppm , Br+Cl < 1500 ppm)

Description

The Everlight 45-21 package has high efficacy, high CRI, low power consumption, wide viewing angle and a compact form factor. These features make this package an ideal LED for all lighting applications.

Applications

- LCD back light
- Mobile phones
- Indicators
- Illumination
- · Switch lights

Expired Period: Forever



Device Selection Guide

Chip Materials	Emitted Color	Resin Color
InGaN	White	Water Clear

Absolute Maximum Ratings (T_{Soldering}=25)

Parameter	Symbol	Rating	Unit
Reverse Voltage	V_{R}	5	V
Forward Current	I _F	30	mA
Peak Forward Current (Duty 1/10 @1KHz)	I _{FP}	100	mA
Power Dissipation	Pd	110	mW
Electrostatic Discharge(HBM)	ESD	1000	V
Operating Temperature	Topr	-40 ~ +85	
Storage Temperature	Tstg	-40 ~ +90	
Soldering Temperature	Tsol	Reflow Soldering: 260 Hand Soldering: 350	for 10 sec. for 3 sec.

Note:

The products are sensitive to static electricity and must be carefully taken when handling products

Electro-Optical Characteristics (T_{Soldering}=25)

Parameter	Symbol	Min.	Тур.	Max.	Unit	Condition
Luminous Intensity	I _V	2100		2600	mcd	I _F =20mA
Forward Voltage	V_{F}	2.9		3.4	V	I _F =20mA
Viewing Angle	2θ _{1/2}		120		deg	I _F =20mA

Notes:

- 1. Tolerance of Luminous Intensity ±11%.
- 2. Tolerance of Forward Voltage: ±0.05V.



Bin Range of Luminous Intensity

Bin Code	Min.	Max.	Unit	Condition
40	2100	2150		
41	2150	2200	_	I _F =20mA
42	2200	2300	_ _ mod	
43	2300	2400	– mcd	
44	2400	2500		
45	2500	2600		

Note:

Tolerance of Luminous Intensity: ±11%

Bin Range of Forward Voltage

Group	Bin Code	Min.	Max.	Unit	Condition
	5-2-3	2.9	3.0		
	6-1-3	3.0	3.1		
E	6-2-3	3.1	3.2	V	I _F =20mA
	7-1-3	3.2	3.3		
	7-2-3	3.3	3.4		

Note:

Tolerance of Forward Voltage: ±0.05V.



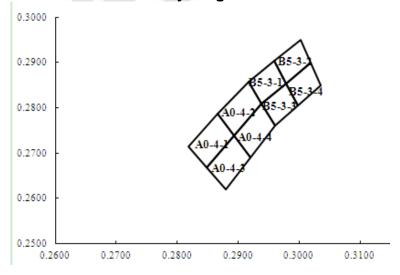
Bin Range of Chromaticity Coordinates

Bin Code	CIE_x	CIE_y	Bin Code	CIE_x	CIE_y
	0.2849	0.2667		0.2894	0.2738
A0-4-1	0.2818	0.2715	A0-4-2	0.2867	0.2786
A0-4-1	0.2867	0.2786	AU-4-2	0.2917	0.2857
	0.2894	0.2738		0.2938	0.2808
	0.2880	0.2620		0.2920	0.2690
A0-4-3	0.2849	0.2667	0044	0.2894	0.2738
A0-4-3	0.2894	0.2738	A0-4-4	0.2938	0.2808
	0.2920	0.2690		0.2960	0.2760
	0.2938	0.2808	B5-3-2	0.2978	0.2854
B5-3-1	0.2917	0.2857		0.2959	0.2903
B0-3-1	0.2959	0.2903		0.3003	0.2950
	0.2978	0.2854		0.3019	0.2900
	0.2960	0.2760		0.2998	0.2805
B5-3-3	0.2938	0.2808	B5-3-4	0.2978	0.2854
D0-3-3	0.2978	0.2854		0.3019	0.2900
	0.2998	0.2805		0.3035	0.2850

Note:

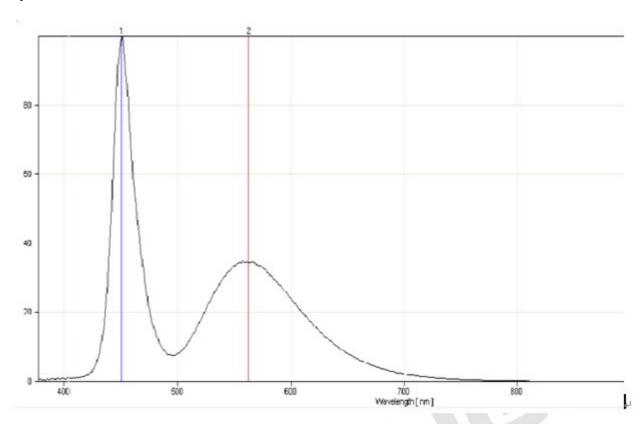
- 1. The value is based on driving current by 20mA.
- 2. Tolerance of Chromaticity Coordinates: ±0.01

The C.I.E. 1931 Chromaticity Diagram





Spectrum Distribution



Typical Electro-Optical Characteristics Curves

Fig.1 - Forward Voltage Shift vs.
Junction Temperature

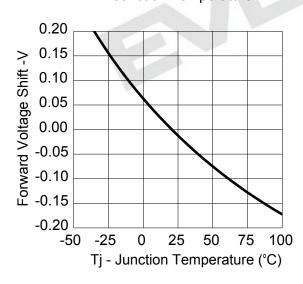
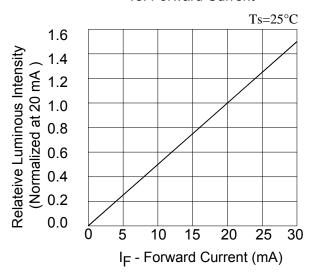


Fig.2 - Relative Luminous Intensity vs. Forward Current





Typical Electro-Optical Characteristics Curves

Fig.3 - Relative Luminous Intensity vs. Junction Temperature

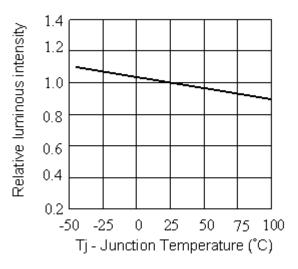


Fig.5 - Max. Driving Forward Current vs. Soldering Temperature

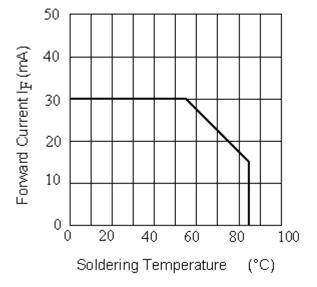


Fig.4 - Forward Current vs. Forward Voltage

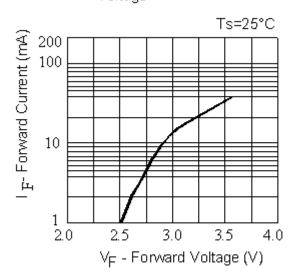
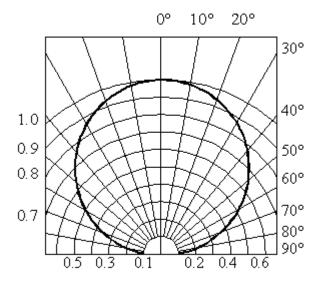
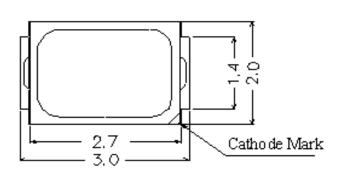


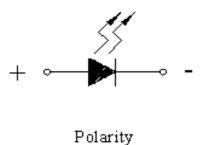
Fig.6 - Radiation Diagram

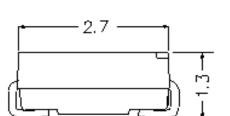


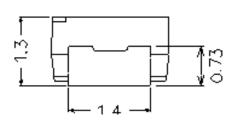


Package Dimension

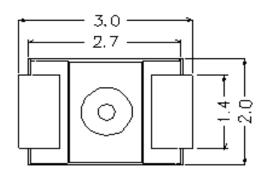


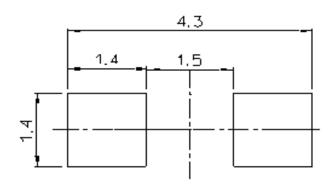






Recommended Solder Pad





Recommended soldering pad design

Note:

Tolerance unless mentioned is ±0.2mm; Unit = mm



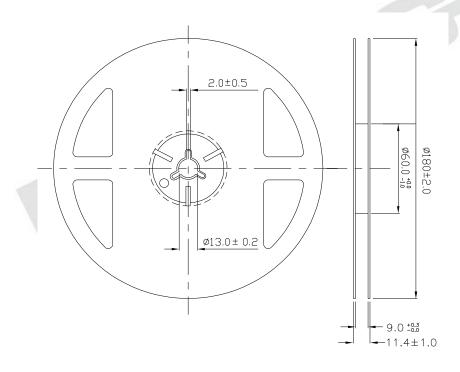
Moisture Resistant Packing Materials

Label Explanation



- CPN: Customer's Product Number
- P/N: Product Number
- QTY: Packing Quantity
- CAT: Luminous Intensity Rank
- HUE: Chromaticity Coordinates
- · REF: Forward Voltage Rank
- · LOT No: Lot Number

Reel Dimensions

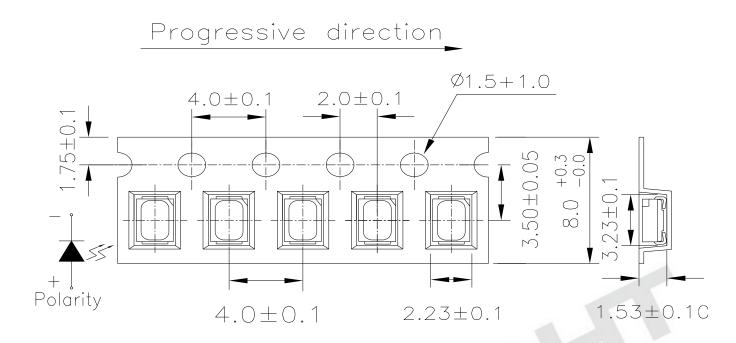


Note:

Tolerances unless mentioned ± 0.1 mm. Unit = mm



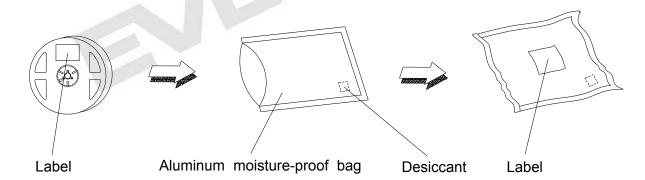
Carrier Tape Dimensions: Loaded Quantity 250/500/1000/2000 pcs Per Reel



Note:

Tolerances unless mentiond ±0.1mm. Unit = mm

Moisture Resistant Packing Process





Reliability Test Items and Conditions

The reliability of products shall be satisfied with items listed below.

Confidence level: 90%

LTPD: 10%

No.	Items	Test Condition	Test Hours/Cycles	Sample Size	Ac/Re
1	Reflow Soldering	Temp.: 260 /10sec.	6 Min.	22 PCS.	0/1
2	Thermal Shock	H:+100 15min 10 sec L:-10 15min	300 Cycles	22 PCS.	0/1
3	Temperature Cycle	H : +100 15min 5 min L : -40 15min	300 Cycles	22 PCS.	0/1
4	High Temperature/Humidity	Ta=85 ,85%RH	1000 Hrs.	22 PCS.	0/1
5	High Temperature Storage	Temp=100	1000 Hrs.	22 PCS.	0/1
6	Low Temperature Storage	Ta=-40	1000 Hrs.	22 PCS.	0/1
7	DC Operating Life	IF = 20 mA / 25	1000 Hrs.	22 PCS.	0/1

LifecyclePhase: Approved



Precautions for Use

1. Over-current-proof

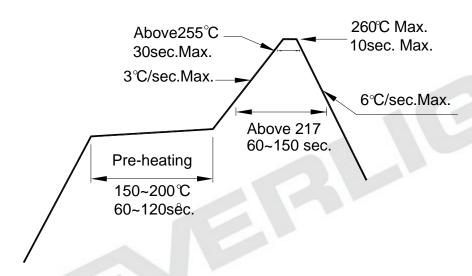
Customer must apply resistors for protection; otherwise slight voltage shift will cause big current change (Burn out will happen).

2. Storage

- 2.1 Do not open moisture proof bag before the products are ready to use.
- 2.2 Before opening the package: The LEDs should be kept at 30 or less and 90%RH or less.
- 2.3 After opening the package: The LED's floor life is 168 Hrs under 30 or less and 60% RH or less. If unused LEDs remain, it should be stored in moisture proof packages.
- 2.4 If the moisture absorbent material (silica gel) has faded away or the LEDs have exceeded the storage time, baking treatment should be performed using the following conditions.
 Baking treatment: 60±5 for 24 hours.

3. Soldering Condition

3.1 Pb-free solder temperature profile



- 3.2 Reflow soldering should not be done more than two times.
- 3.3 When soldering, do not put stress on the LEDs during heating.
- 3.4 After soldering, do not warp the circuit board.

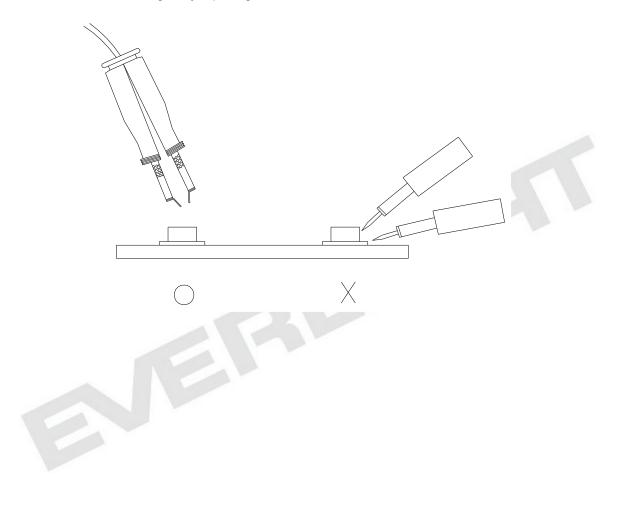


4. Soldering Iron

Each terminal is to go to the tip of soldering iron temperature less than 350 for 3 seconds within once in less than the soldering iron capacity 25W. Leave two seconds and more intervals, and do soldering of each terminal. Be careful because the damage of the product is often started at the time of the hand solder.

5. Repairing

Repair should not be done after the LEDs have been soldered. When repairing is unavoidable, a double-head soldering iron should be used (as below figure). It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.



Expired Period: Forever